TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20261028000.1**	**PCN Issued**	November 02, 2026
Qualification of DBUMP Sn/Ag material change affecting GNZ and GDK package devices		**Sample request deadline:**	January 01, 2027
		Estimated 1st ship date:	January 31, 2027
***Sample requests received after** January 01, 2027* **will not be supported.**			

Change type(s)
Wafer Fab Material

PCN Details

Description of Change:

Texas Instruments is pleased to announce a bump material change for the affected GNZ and GDK package devices. The devices proposed for the change are listed in the "Product Affected" section.

Material differences are as follows:

	Current	**New**
Bump solder ball or attach solder material composition	SnPb	SnAg

Qual details are provided in the Qual Data Section.

Reason for Change:	Discontinued material

Anticipated impact on Form, Fit, Function, Quality or Reliability:	None
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☐ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:	None; Request the Supporting Data Packet for more details on the change.

Products Affected:

TMS320C6412ACNZ5	TMS320DM640ACDKA4	TMS320DM642AGDKA6	TMS320DM643ACNZ6
TMS320C6412ACNZ7	TMS320DM640AGNZ4	TMS320DM642AGNZA5	TMS320DM643AGNZ5
TMS320C6412AGDKA5	TMS320DM642AGDKA5	TMS320DM642AGNZA6	

ZENO2 (DM5) qualification of DBUMP Sn/Ag Pb-free bump
Approve Date 25-AUGUST -2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TMS320DM642AGNZA6	Qual Device: TMS320DM642AGDKA6
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	3/231/0	3/231/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device TMS320DM642AGNZA6 is qualified at MSL4 260C
- Qual Device TMS320DM642AGDKA6 is qualified at MSL4 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2506-065

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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